Agenda

7:30	Registration opens – continental breakfast will be served
8:45 am – 9:00 am	Welcome
9:00 am -9:30 am	**Keynote: A Revolution in Systems Integration as CMOS Scaling Slows** Wilmer (Bill) R. Bottoms, Ph.D., Chairman Third Millennium Test Solutions
9:30 am – 10:30 am	**Panel: Can the Packaging Community Establish a Real Design for Heterogeneous Integration Ecosystem?** Moderator: Rich Rice, Senior Vice President of Sales, North America ASE (U.S.) Inc. **Panelists:** • **Ramakanth Alapati** VP, Strategic Development, Amkor Technology, Inc. • **Farhang Yazdani** President & CEO, BroadPak Corporation • **Kevin Rinebold** Technology Manager, Advanced Packaging Solutions, Mentor • **Jawad Nasrullah, Ph.D.** Co-founder, President and CTO, zGlue • **Others to be announced**
10:30 am – 11:00 am	**Break in Exhibit Area**
11:00 am – 11:30 am	**Keynote: Heterogenous Integration – a Systems-level Reliability Perspective** Krishna Darbha, Ph.D., Senior Director of Reliability at the Microsoft Devices Business Group (MDG) Microsoft
11:30 am – 12:30 pm	**Panel: Should We Rethink the Reliability Standards for Heterogeneous Integrated SIP Packages?** Moderator: Gamal Refai-Ahmed, Ph.D. Distinguished Engineer at Xilinx, ASME Life Fellow ASME *Panelists listed on page two*

*** Continued on page two ***

Reliability Standards Panelists:

- **Krishna Darbha, Ph.D.**
  Senior Director of Reliability at the Microsoft Devices Business Microsoft
- **Abhijit Dasgupta, Ph.D.**
  Jeong H. Kim Professor, Department of Mechanical Engineering, University of Maryland
- **Suresh Ramalingam, PhD.**
  Fellow, Manager Advanced Packaging Interconnect Technology Development , Xilinx
- **Milena Vujosevic, Ph.D.**
  Principal Engineer, Senior Technology Development Manager, Intel

12:30 pm – 1:30 pm **Lunch in Exhibit Area**

1:30 pm – 2:00 pm **Keynote: Test Challenges for Heterogeneous Device Integration**
Dave Armstrong, Director, Business Development,
Advantest America, Inc.

2:00 pm – 3:00 pm **Panel: What are the Best Test Strategies and Guiding Principles for Heterogeneous Integrations?**
Moderator: Robin Wei, STATS ChipPAC

Panelists:

- **Gerard John**
  Sr. Director, Advanced Packaging R&D, Amkor Technology
- **Amy Leong**
  Senior Vice President, Marketing & Customer Solutions, Form Factor
- **Keith Schaub**
  Vice President Corporate Business Development, W2BI/Advantest
- **Others to be announced**

3:00 pm – 3:30 pm **Break in Exhibit Area**

3:30 pm – 4:30 pm **Panel Summaries/Key Points**
Transcribers:

- **Jeff Demmin**
  Senior Lead Scientist at Booz Allen Hamilton
- **Herb Reiter**
  President of eda 2 asic Consulting, Inc.
- **Paul Werbaneth**
  Global Product Marketing Director, Intevac, Inc.

4:30 pm – 4:45 pm Wrap-up
4:45 pm – 6:15 pm **Reception in Exhibit Area**